

Epoxy preform guidelines for RF microwave module assembly

Speaker: **Scott MacKenzie**, President, Bonding Source, Manchester NH 03103

Email: smackenzie@bondingsource.com

Abstract

Conductive and insulating epoxy film options available to RF Microwave module manufacturers have increase dramatically over the last 15 years. Converting options are no longer limited to hand cutting small batches or die cutting high volume requirements. The advent of laser cutting preforms is now well established and offers a solution to the industry for any batch size. As module manufacturers become more sophisticated, preform converting has evolved to help improve module performance, process control, manufacturability, and overall quality. Effective pre-form drawings now contain information that is essential for meeting the requirements of demanding manufacturers. This presentation outlines these parameters and shares guidelines used by tier one defense and aerospace companies. The information is geared toward engineering, manufacturing, and quality professionals involved in RF microwave module design and assembly.